

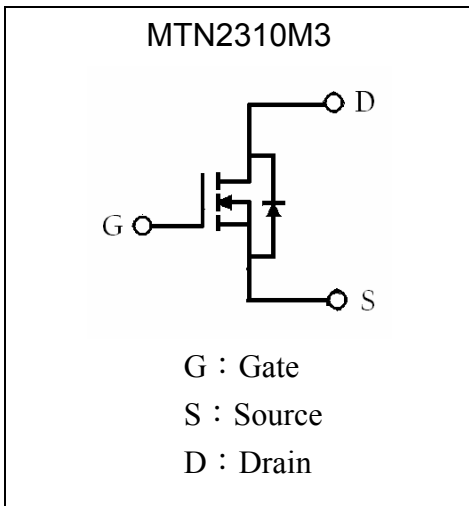
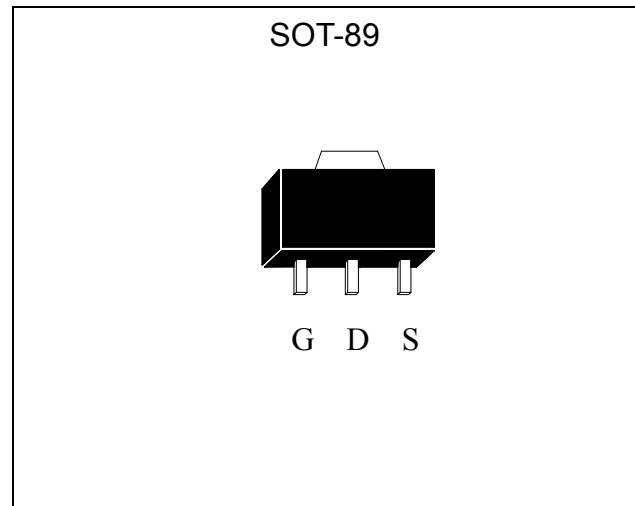
60V N-Channel Enhancement Mode MOSFET

MTN2310M3

BV _{DSS}	60V
I _D	4.8A
R _{DS(on)} @V _{GS} =10V, I _D =4A	41mΩ (typ)
R _{DS(on)} @V _{GS} =5V, I _D =3A	46mΩ (typ)

Features

- Simple drive requirement
- Small package outline
- Pb-free lead plating package

Symbol

Outline

Absolute Maximum Ratings (T_a=25°C)

Parameter	Symbol	Limits	Unit
Drain-Source Voltage	V _{DS}	60	V
Gate-Source Voltage	V _{GS}	±20	V
Continuous Drain Current @ T _A =25°C (Note 3)	I _D	4.8	A
Continuous Drain Current @ T _A =70°C (Note 3)		3.8	A
Pulsed Drain Current (Notes 1, 2)	I _{DM}	20	A
Maximum Power Dissipation @ T _A =25°C	P _D	2 (Note 3)	W
Linear Derating Factor		0.01	W/°C
Operating Junction Temperature	T _j	-55~+150	°C
Storage Temperature	T _{stg}	-55~+150	°C

Note : 1. Pulse width limited by maximum junction temperature.

2. Pulse width ≤ 300μs, duty cycle ≤ 2%.

 3. When the device is surface mounted on 1 in² copper pad of FR-4 board with 2 oz. copper, t ≤ 10s.



Thermal Performance

Parameter	Symbol	Limit	Unit
Thermal Resistance, Junction-to-Ambient(PCB mounted)	Rth,ja	62.5 (Note)	°C/W

Note : When the device is surface mounted on 1 in² copper pad of FR-4 board with 2 oz. copper, t≤10s.

Electrical Characteristics (Tj=25°C, unless otherwise noted)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Static					
BV _{DSS}	60	-	-	V	V _{GS} =0, I _D =250μA
V _{GS(th)}	1.0	1.8	3.0	V	V _{DS} =V _{GS} , I _D =250μA
I _{GSS}	-	-	±100	nA	V _{GS} =±20V, V _{DS} =0
I _{DSS}	-	-	1	μA	V _{DS} =48V, V _{GS} =0
	-	-	25		V _{DS} =40V, V _{GS} =0 (Tj=70°C)
*R _{DSON}	-	41	55	mΩ	I _D =4A, V _{GS} =10V
	-	46	65		I _D =3A, V _{GS} =5V
*G _{FS}	-	9	-	S	V _{DS} =5V, I _D =10A
Dynamic					
C _{iSS}	-	1128	-	pF	V _{DS} =30V, V _{GS} =0, f=1MHz
C _{oSS}	-	42	-		
C _{rSS}	-	32	-		
t _{d(ON)}	-	12	-	ns	V _{DS} =30V, I _D =1A, V _{GS} =10V, R _G =6Ω
t _r	-	18	-		
t _{d(OFF)}	-	32	-		
t _f	-	6	-		
Q _g	-	14	-	nC	V _{DS} =48V, I _D =4.8A, V _{GS} =10V
Q _{gs}	-	3.8	-		
Q _{gd}	-	4.6	-		
Source-Drain Diode					
*I _S	-	-	4	A	
*I _{SM}	-	-	20		
*V _{SD}	-	-	1.3	V	V _{GS} =0V, I _F =I _S
T _{rr}	-	15	-	ns	V _{GS} =0V, I _F =5A, dI/dt=100A/μs
Q _{rr}	-	8	-	nC	

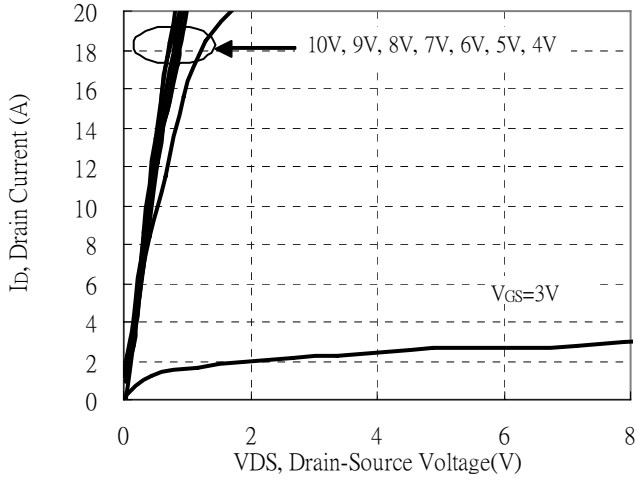
*Pulse Test : Pulse Width ≤300μs, Duty Cycle≤2%

Ordering Information

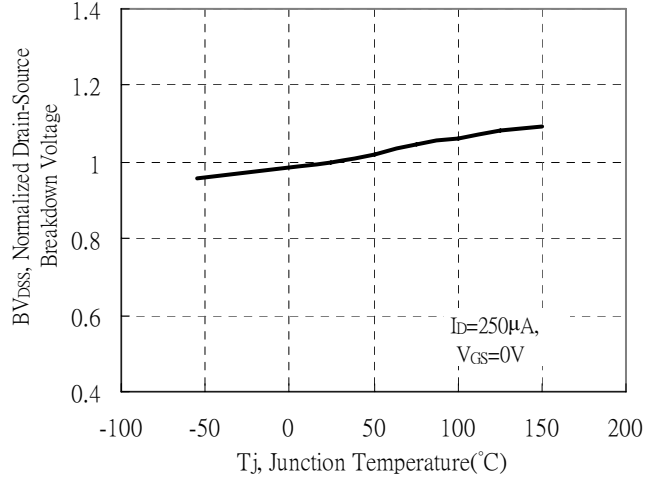
Device	Package	Shipping	Marking
MTN2310M3	SOT-89 (Pb-free lead plating package)	1000 pcs / Tape & Reel	2310

Typical Characteristics

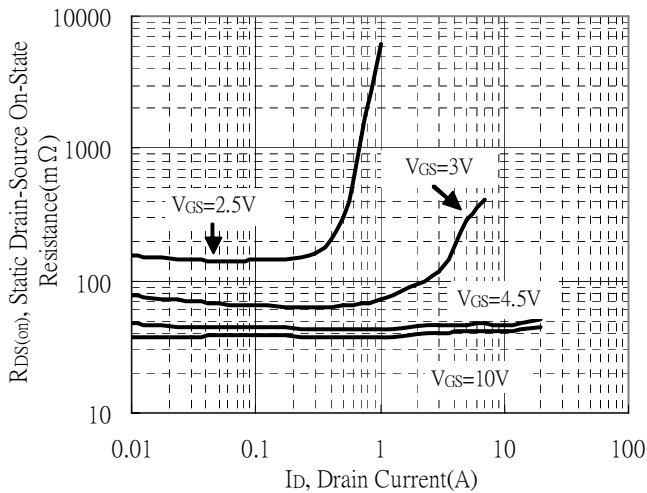
Typical Output Characteristics



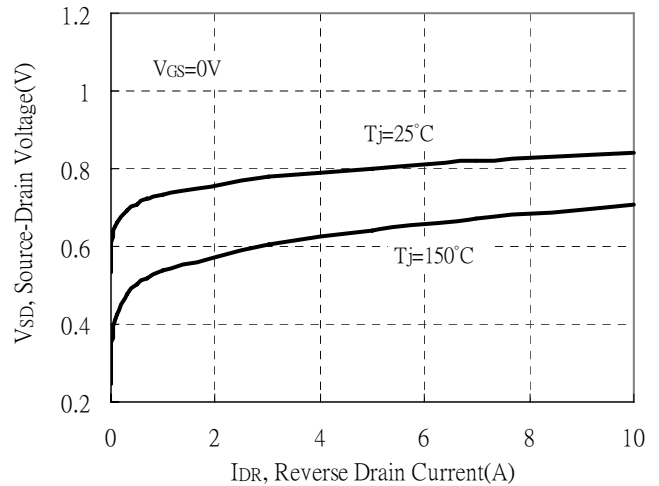
Breakdown Voltage vs Ambient Temperature



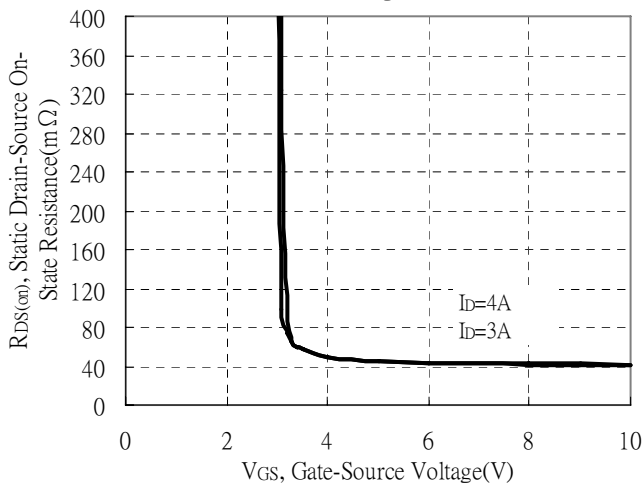
Static Drain-Source On-State resistance vs Drain Current



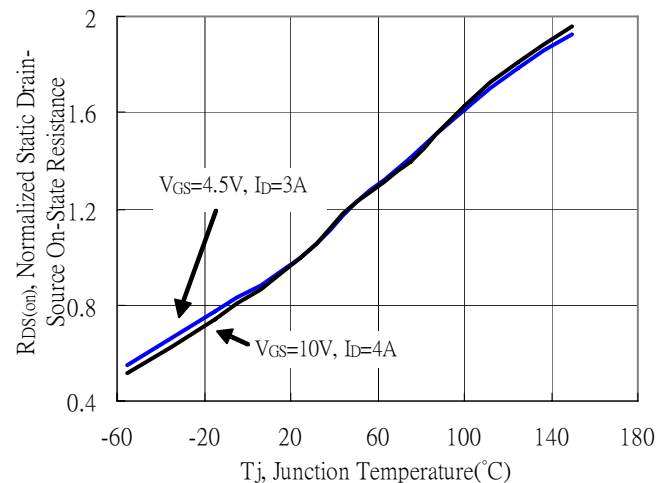
Reverse Drain Current vs Source-Drain Voltage



Static Drain-Source On-State Resistance vs Gate-Source Voltage



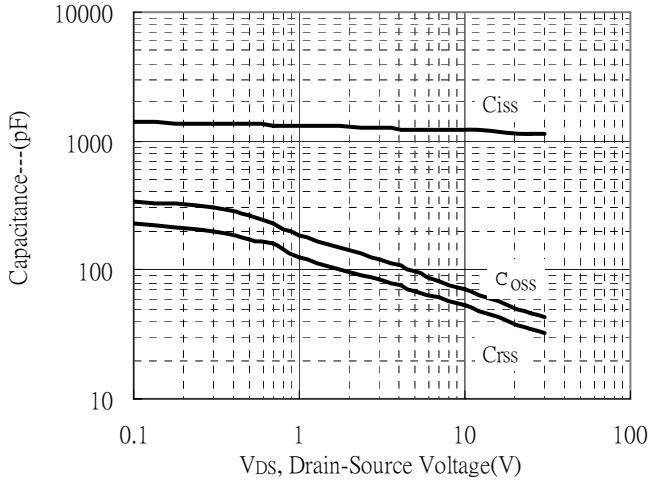
Drain-Source On-State Resistance vs Junction Temperature



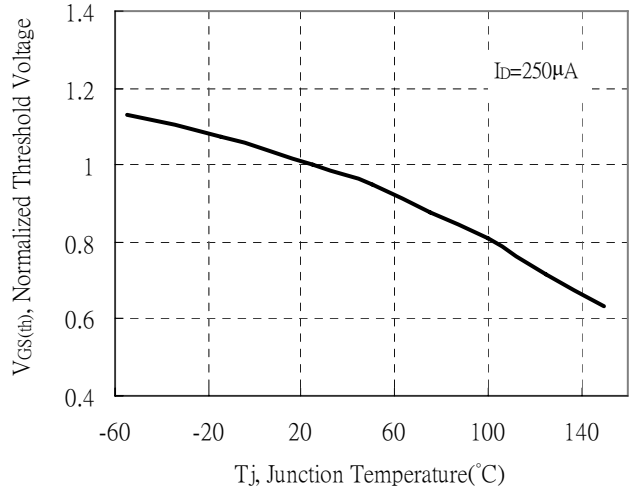


Typical Characteristics(Cont.)

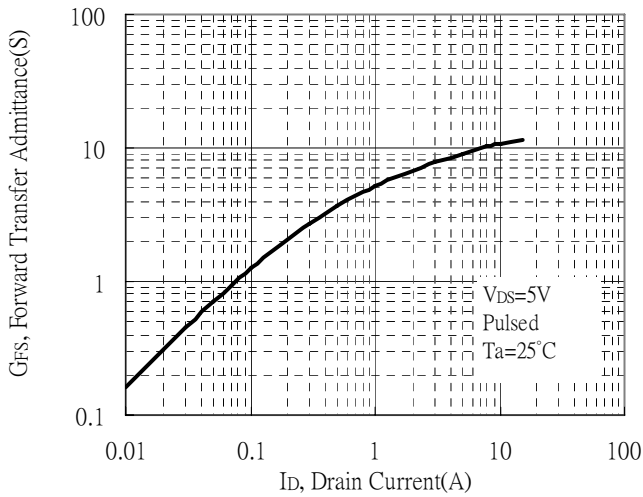
Capacitance vs Drain-to-Source Voltage



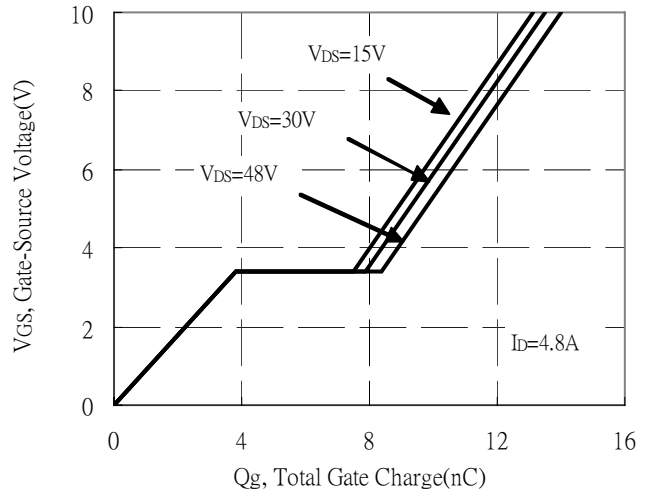
Threshold Voltage vs Junction Temperature



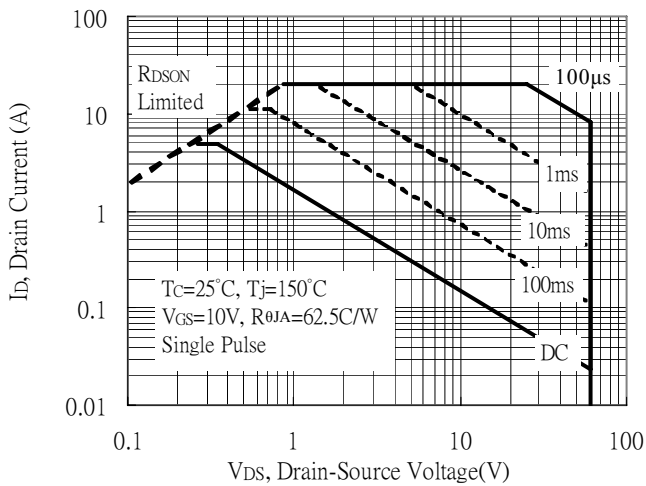
Forward Transfer Admittance vs Drain Current



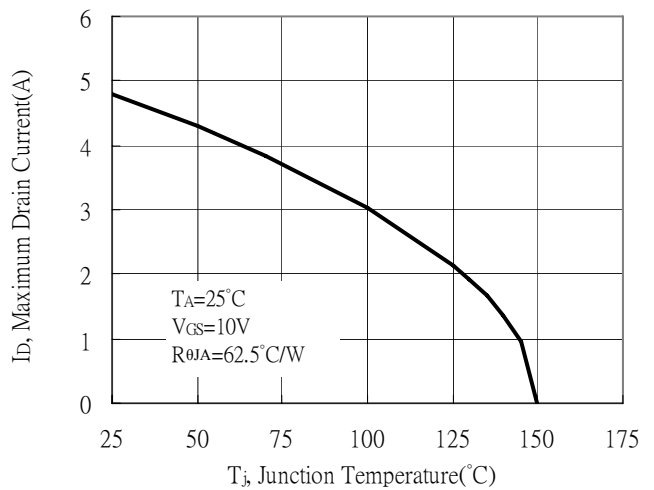
Gate Charge Characteristics



Maximum Safe Operating Area

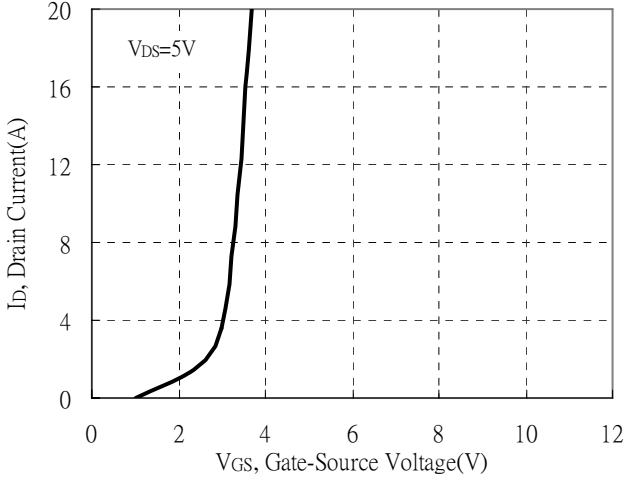


Maximum Drain Current vs Junction Temperature

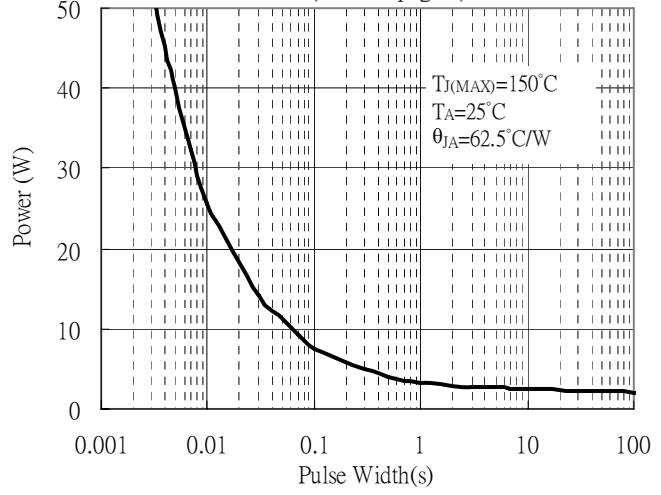


Typical Characteristics(Cont.)

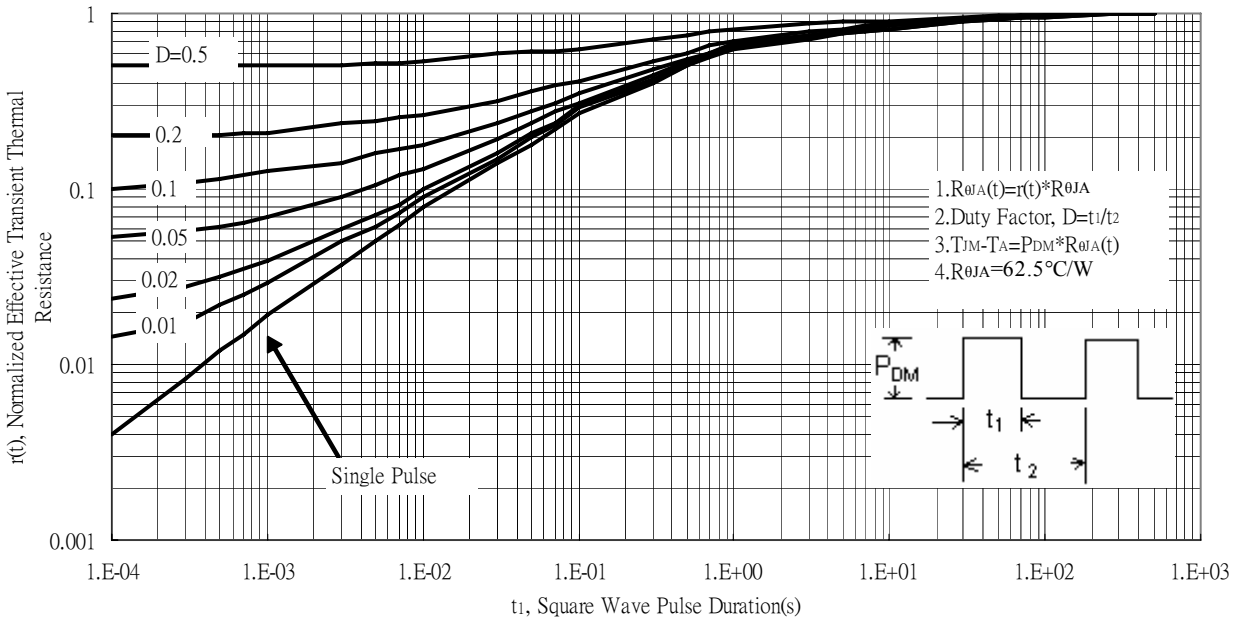
Typical Transfer Characteristics



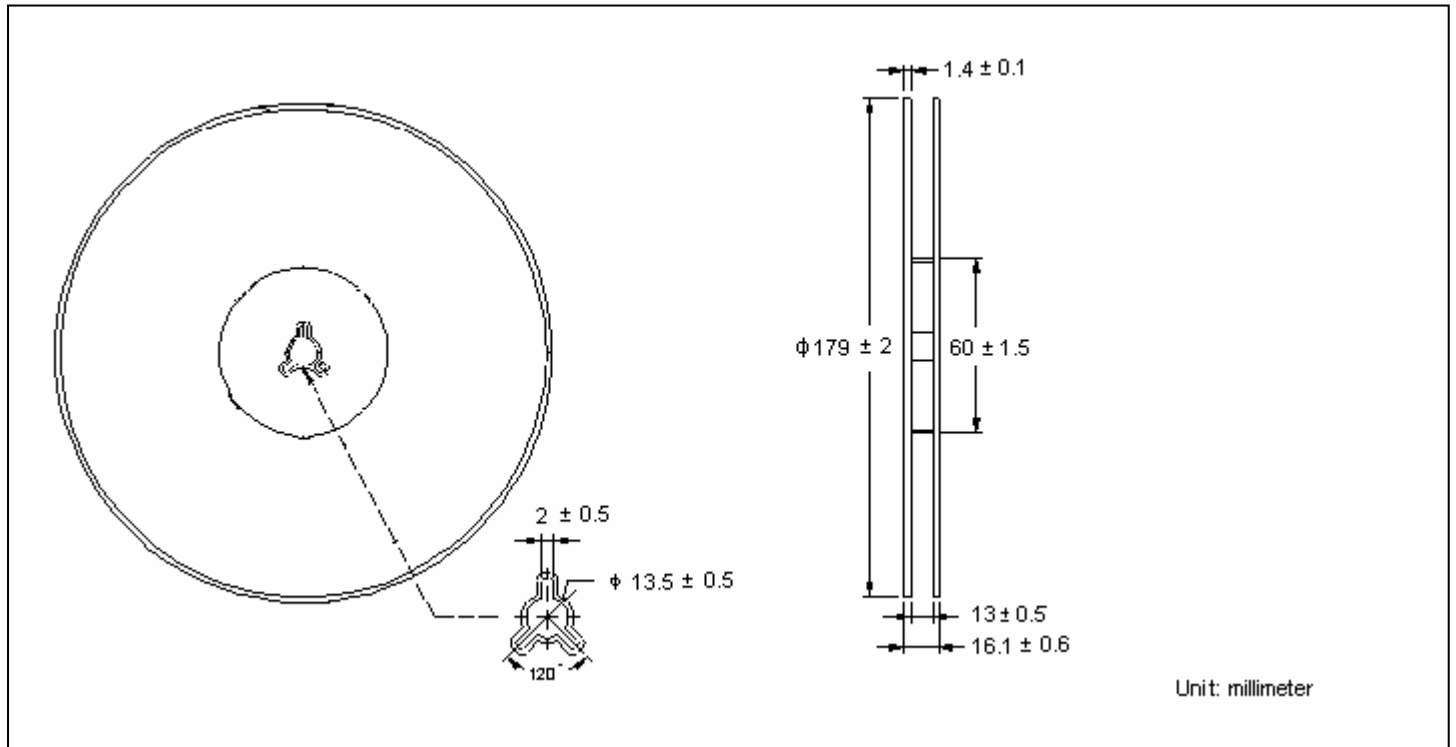
Single Pulse Power Rating, Junction to Ambient
 (Note on page 2)



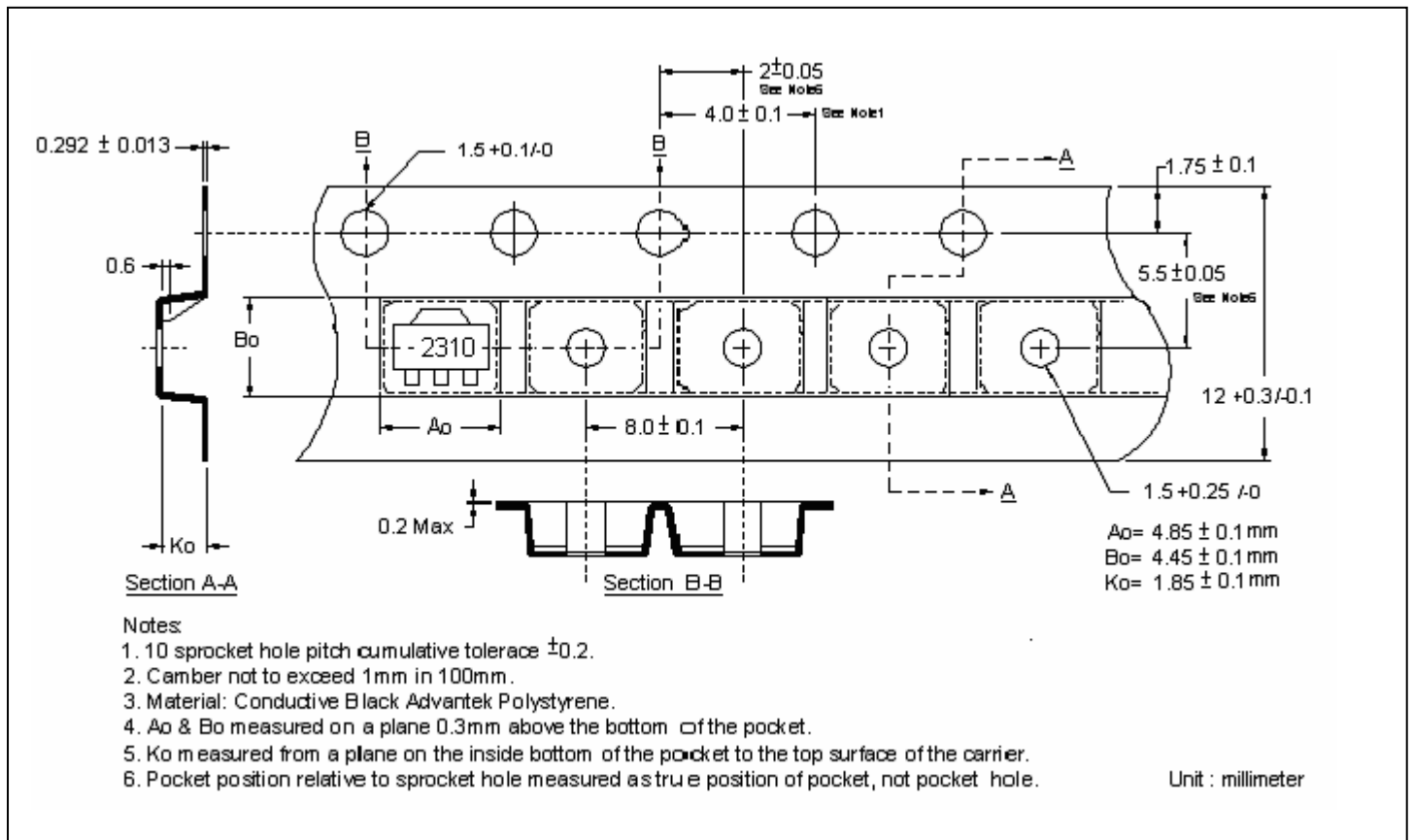
Transient Thermal Response Curves



Reel Dimension

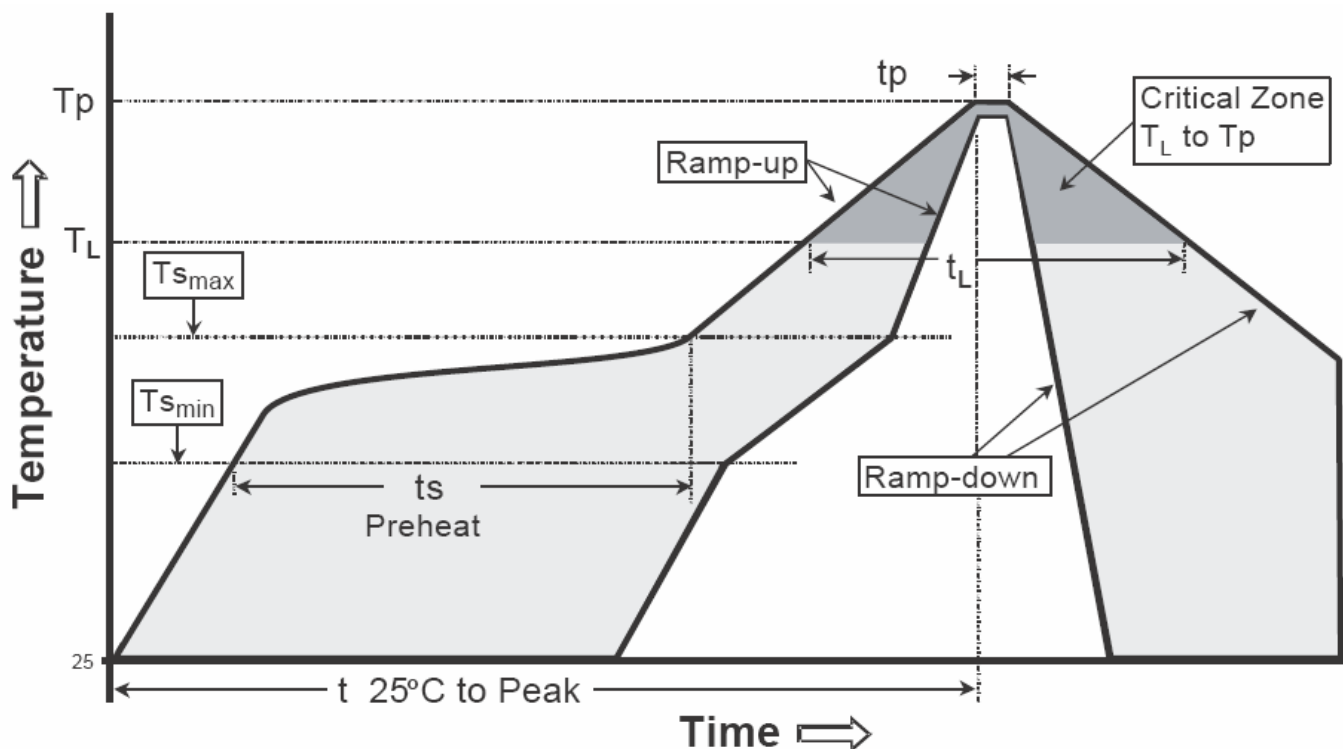


Carrier Tape Dimension



Recommended wave soldering condition

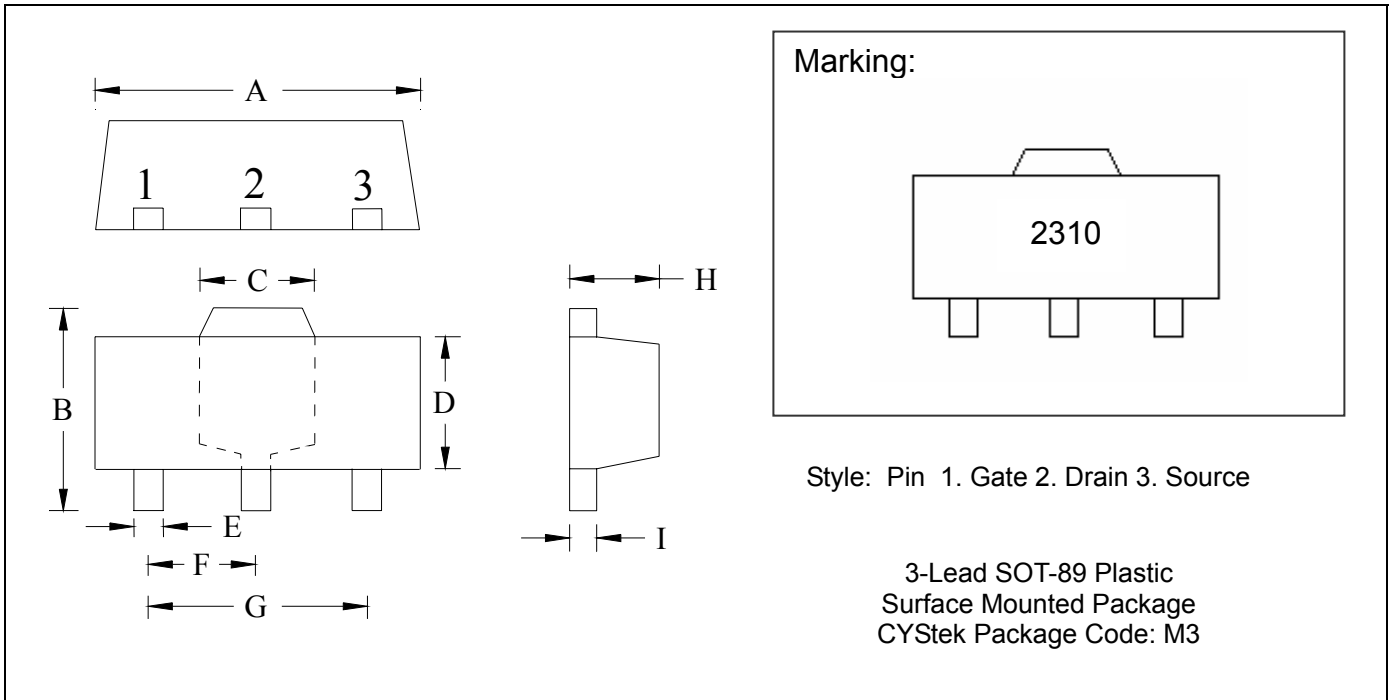
Product	Peak Temperature	Soldering Time
Pb-free devices	260 +0/-5 °C	5 +1/-1 seconds

Recommended temperature profile for IR reflow


Profile feature	Sn-Pb eutectic Assembly	Pb-free Assembly
Average ramp-up rate (T _s max to T _p)	3°C/second max.	3°C/second max.
Preheat		
-Temperature Min(T _s min)	100°C	150°C
-Temperature Max(T _s max)	150°C	200°C
-Time(t _s min to t _s max)	60-120 seconds	60-180 seconds
Time maintained above:		
-Temperature (T _L)	183°C	217°C
- Time (t _L)	60-150 seconds	60-150 seconds
Peak Temperature(T _P)	240 +0/-5 °C	260 +0/-5 °C
Time within 5°C of actual peak temperature(tp)	10-30 seconds	20-40 seconds
Ramp down rate	6°C/second max.	6°C/second max.
Time 25 °C to peak temperature	6 minutes max.	8 minutes max.

Note : All temperatures refer to topside of the package, measured on the package body surface.

SOT-89 Dimension



DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.1732	0.1811	4.40	4.60	F	0.0591	TYP	1.50	TYP
B	0.1551	0.1673	3.94	4.25	G	0.1181	TYP	3.00	TYP
C	0.0610	REF	1.55	REF	H	0.0551	0.0630	1.40	1.60
D	0.0906	0.1024	2.30	2.60	I	0.0138	0.0173	0.35	0.44
E	0.0126	0.0205	0.32	0.52					

Notes: 1.Controlling dimension: millimeters.
 2.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
 3.If there is any question with packing specification or packing method, please contact your local CYStek sales office.

Material:

- Lead: Pure tin plated.
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0.

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